



Material Content Data Sheet



Sales Product Name		BSL302SN H6327		Issued		22. January 2018		
MA#		MA001190006						
Package		PG-TSOP6-6-6		Weight*		13.59 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.010	0.07		726	
	noble metal	gold	7440-57-5	0.038	0.28		2814	
	inorganic material	silicon	7440-21-3	0.583	4.29	4.64	42923	46463
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		87	
	non noble metal	titanium	7440-32-6	0.006	0.04		435	
	non noble metal	chromium	7440-47-3	0.018	0.13		1304	
	non noble metal	copper	7440-50-8	5.882	43.28	43.46	432710	434536
encapsulation	organic material	carbon black	1333-86-4	0.066	0.48		4840	
	plastics	epoxy resin	-	1.415	10.41		104069	
	inorganic material	silicondioxide	60676-86-0	5.099	37.51	48.40	375134	484043
leadfinish	non noble metal	tin	7440-31-5	0.299	2.20	2.20	21989	21989
plating	noble metal	silver	7440-22-4	0.176	1.30	1.30	12969	12969
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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